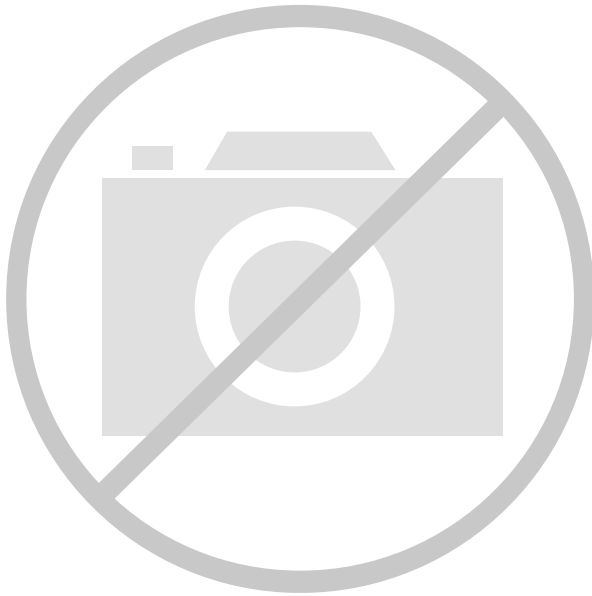




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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	-
Number of Macrocells	320
Number of Gates	-
Number of I/O	120
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	160-BQFP
Supplier Device Package	160-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m5lv-320-120-7yc



Table 1. MACH 5 Device Features ¹

Feature	M5-128/1 M5LV-128		M5-192/1	M5-256/1 M5LV-256		M5-320 M5LV-320		M5-384 M5LV-384		M5-512 M5LV-512	
Supply Voltage (V)	5	3.3	5	5	3.3	5	3.3	5	3.3	5	3.3
Macrocells	128	128	192	256	256	320	320	384	384	512	512
Maximum User I/O Pins	120	120	120	160	160	192	160	160	160	256	256
t _{PD} (ns)	5.5	5.5	5.5	5.5	5.5	6.5	6.5	6.5	6.5	6.5	6.5
t _{SS} (ns)	3.0	3.0	3.0	3.0	3.0	3.0	3.0	3.0	3.0	3.0	3.0
t _{COS} (ns)	4.5	4.5	4.5	4.5	4.5	5.0	5.0	5.0	5.0	5.0	5.0
f _{CNT} (MHz)	182	182	182	182	182	167	167	167	167	167	167
Typical Static Power (mA)	35	35	45	55	55	70	70	75	75	100	100
IEEE 1149.1 Boundary Scan Compliant	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PCI-Compliant	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes

Note:

1. "M5-xxx" is for 5-V devices. "M5LV-xxx" is for 3.3-V devices.

GENERAL DESCRIPTION

The MACH[®] 5 family consists of a broad range of high-density and high-I/O Complex Programmable Logic Devices (CPLDs). The fifth-generation MACH architecture yields fast speeds at high CPLD densities, low power, and supports additional features such as in-system programmability, Boundary Scan testability, and advanced clocking options (Table 1). The MACH 5 family offers 5-V (M5-xxx) and 3.3-V (M5LV-xxx) operation.

Manufactured in state-of-the-art ISO 9000 qualified fabrication facilities on E²CMOS process technologies, MACH 5 devices are available with pin-to-pin delays as fast as 5.5 ns (Table 2). The 5.5, 6.5, 7.5, 10, and 12-ns devices are compliant with the *PCI Local Bus Specification*.

Select devices have been discontinued.
See Ordering Information section for product status.

and both the 3.3-V and the 5-V device versions are in-system programmable through an IEEE 1149.1 Test Access Port (TAP) interface.

FUNCTIONAL DESCRIPTION

The MACH 5 architecture consists of PAL blocks connected by two levels of interconnect. The **block interconnect** provides routing among 4 PAL blocks. This grouping of PAL blocks joined by the block interconnect is called a **segment**. The second level of interconnect, the **segment interconnect**, ties all of the segments together. The only logic difference between any two MACH 5 devices is the number of segments. Therefore, once a designer is familiar with one device, consistent performance can be expected across the entire family. All devices have four clock pins available which can also be used as logic inputs.

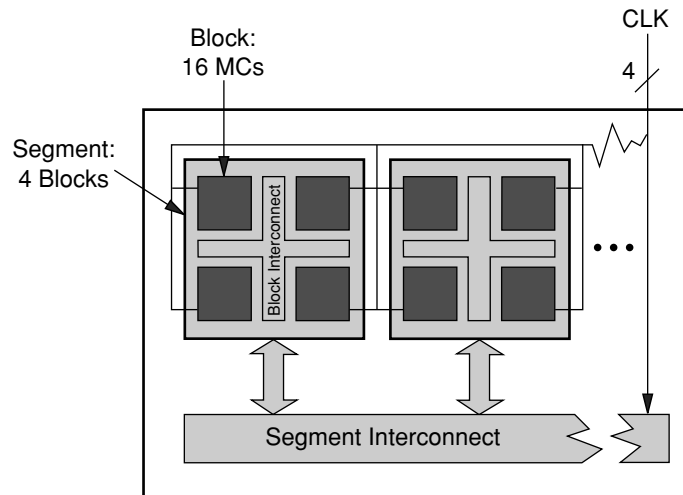


Figure 1. MACH 5 Block Diagram

20446G-001

The MACH 5 PAL blocks consist of the elements listed below (Figure 2). While each PAL block resembles an independent PAL device, it has superior control and logic generation capabilities.

- ◆ I/O cells
- ◆ Product-term array and Logic Allocator
- ◆ Macrocells
- ◆ Register control generator
- ◆ Output enable generator

I/O Cells

The I/Os associated with each PAL block have a path directly back to that PAL block called **local feedback**. If the I/O is used in another PAL block, the **interconnect feeder** assigns a **block interconnect** line to that signal. The interconnect feeder acts as an input switch matrix. The block and segment interconnects provide connections between any two signals in a device. The **block feeder** assigns block interconnect lines and local feedback lines to the PAL block inputs.

Select devices have been discontinued.
See Ordering Information section for product status.

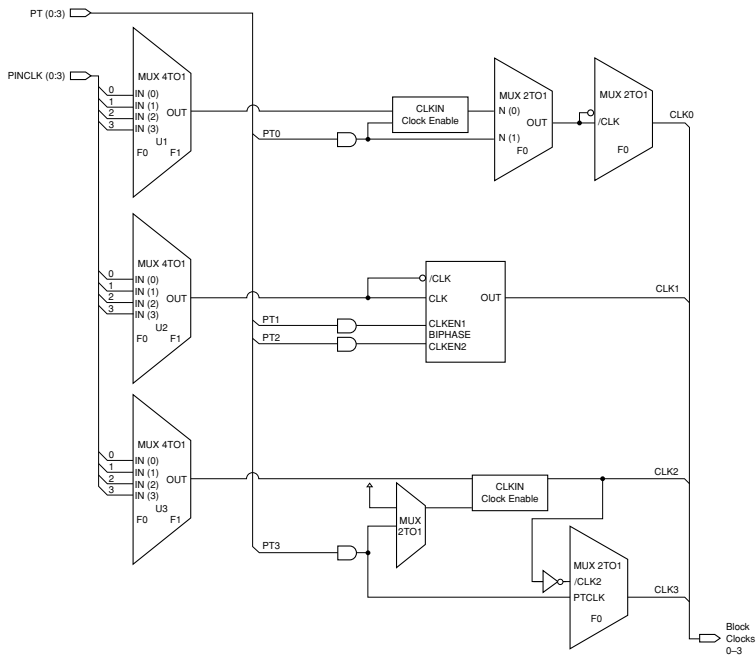
- ◆ Global clock (0, 1, 2, or 3) with positive and negative edge clock enable (biphase)

Clock Line 2 Options

- ◆ Global clock (0, 1, 2, or 3) with clock enable

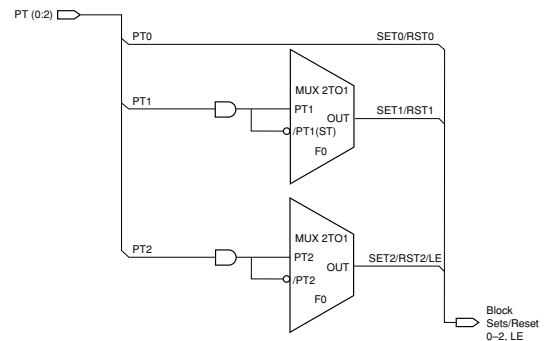
Clock Line 3 Options

- ◆ Complement of clock line 2 (same clock enable)
- ◆ Product-term clock (if clock line 2 does not use clock enable)



20446G-004

Figure 4. Clock Generator



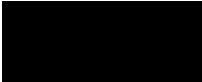
20446G-005

Figure 5. Set/Reset Generator

The set/reset generation portion of the control generator (Figure 5) creates three set/reset lines for the PAL block. Each macrocell can choose one of these three lines or choose no set/reset at all. All three lines can be configured for product term set/reset and two of the three lines can be configured as sum term set/reset and one of the lines can be configured as product-term or sum-term latch enable. While the set/reset signals are generated in the control generator, whether that signal sets or resets a flip-flop is determined within the individual macrocell. The same signal can set one flip-flop and reset another. PT2 or /PT2 can also be used as a latch enable for macrocells configured as latches.

**Select devices have been discontinued.
See Ordering Information section for product status.**

**Select devices have been discontinued.
See Ordering Information section for product status.**



MULTIPLE I/O AND DENSITY OPTIONS

The MACH 5 family offers six macrocell densities in a number of I/O options. This allows designers to choose a device close to their logic density and I/O requirements, thus minimizing costs. For the same package type, every density has the same pin-out. With proper design considerations, a design can be moved to a higher or lower density part as required.

IEEE 1149.1 - COMPLIANT BOUNDARY SCAN TESTABILITY

Most MACH 5 devices have boundary scan registers and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more complete board-level testing.

IEEE 1149.1 - COMPLIANT IN-SYSTEM PROGRAMMING

Programming devices in-system provides a number of significant benefits including: rapid prototyping, lower inventory levels, higher quality, and the ability to make in-field modifications. All MACH 5 devices provide in-system programming (ISP) capability through their IEEE 1149.1-compliant Boundary Scan Test Access Port. By using the IEEE 1149.1-compliant Boundary Scan Test Access Port as the communication interface through which ISP is achieved, customers get the benefit of a standard, well-defined interface.

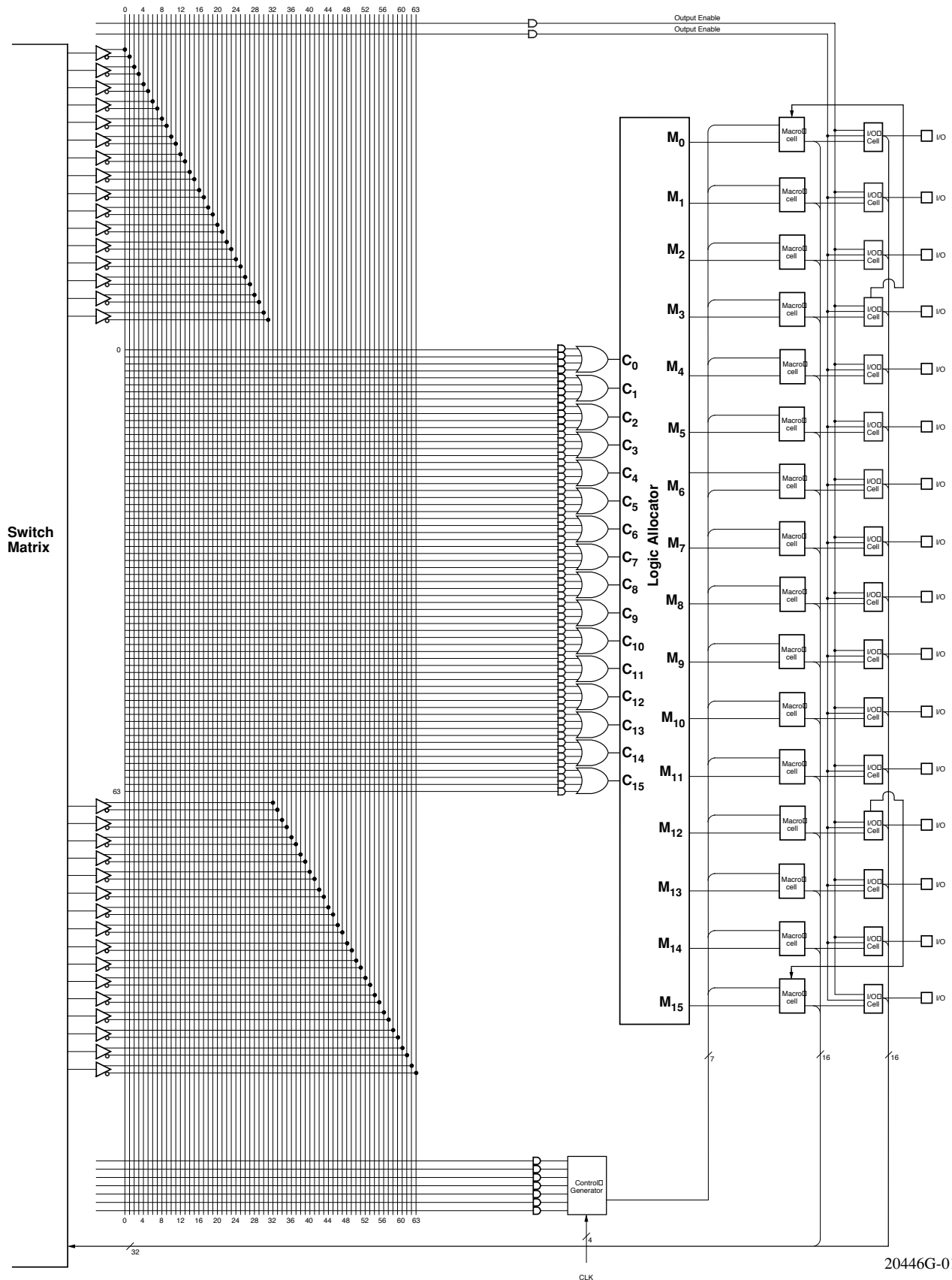
MACH 5 devices can be programmed across the commercial temperature and voltage range. The PC-based LatticePRO software facilitates in-system programming of MACH 5 devices. LatticePRO software takes the JEDEC file output produced by design implementation software, along with information about the Boundary Scan chain, and creates a set of vectors that are used to drive the Boundary Scan chain. LatticePRO software can use these vectors to drive a Boundary Scan chain via the parallel port of a PC. Alternatively, LatticePRO software can output files in formats understood by common automated test equipment. This equipment can then be used to program MACH 5 devices during the testing of a circuit board.

PCI COMPLIANT

MACH 5 devices in the -5/-6/-7/-10/-12 speed grades are compliant with the *PCI Local Bus Specification* version 2.1, published by the PCI Special Interest Group (SIG). The 5-V devices are fully PCI-compliant. The 3.3-V devices are mostly compliant but do not meet the PCI condition to clamp the inputs as they rise above V_{CC} because of their 5-V input tolerant feature. MACH 5 devices provide the speed, drive, density, output enables and I/Os for the most complex PCI designs.

Select devices have been discontinued.
See Ordering Information section for product status.

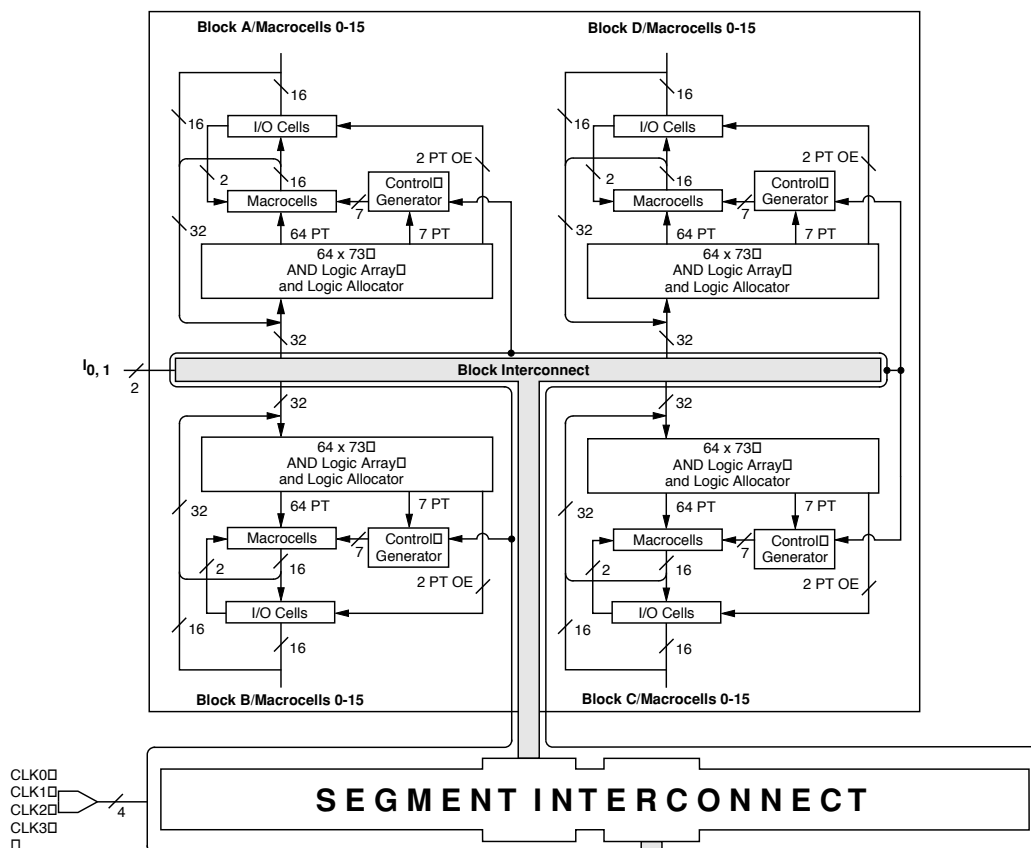
MACH 5 PAL BLOCK



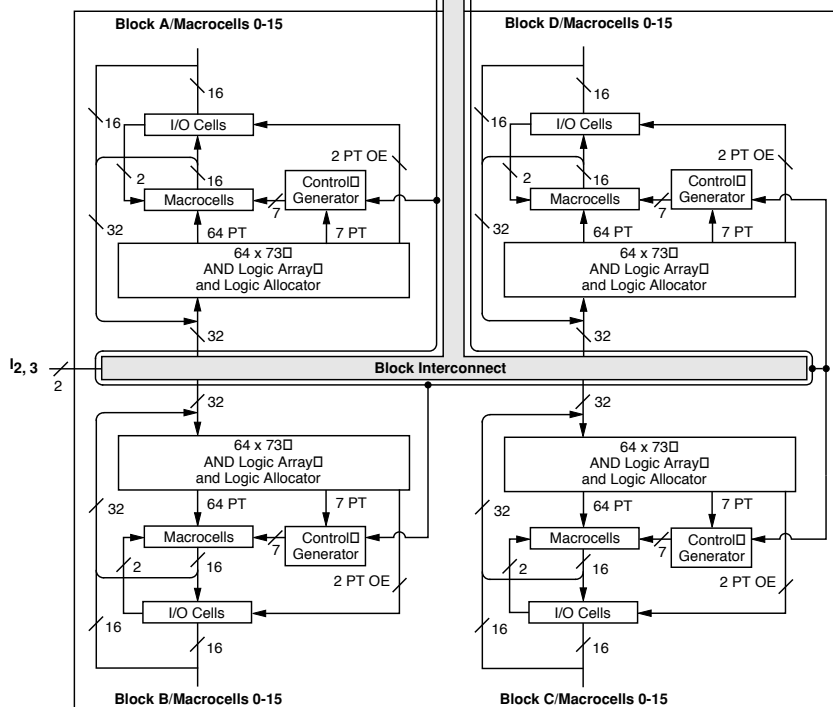
Select devices have been discontinued.
See Ordering Information section for product status.

BLOCK DIAGRAM — M5(LV)-128/XXX

SEGMENT 0



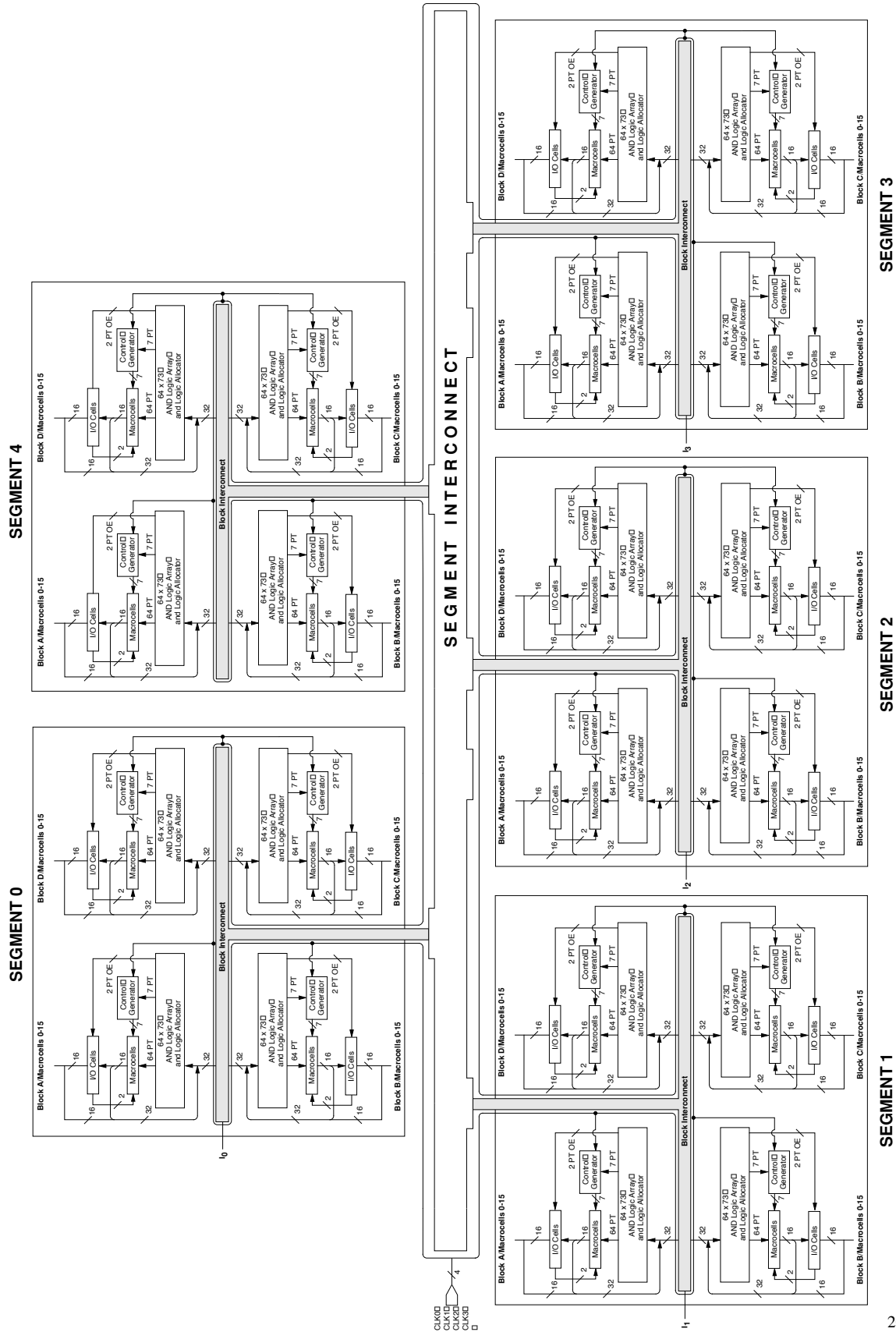
SEGMENT 1



Select devices have been discontinued.
See Ordering Information section for product status.

20446G-007

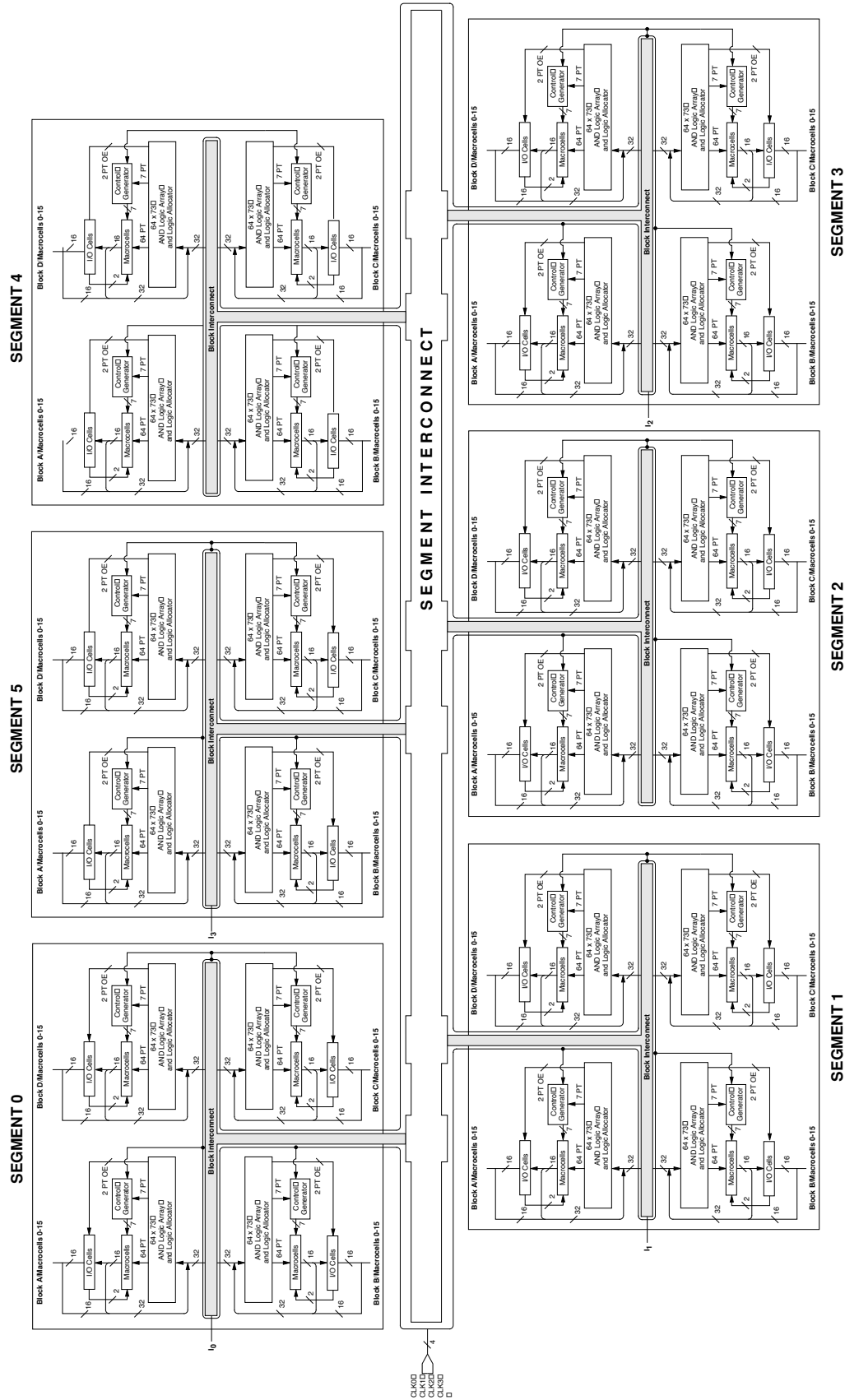
BLOCK DIAGRAM — M5(LV)-320/XXX



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See Ordering Information section for product status.

20446G-010

BLOCK DIAGRAM — M5(LV)-384/XXX

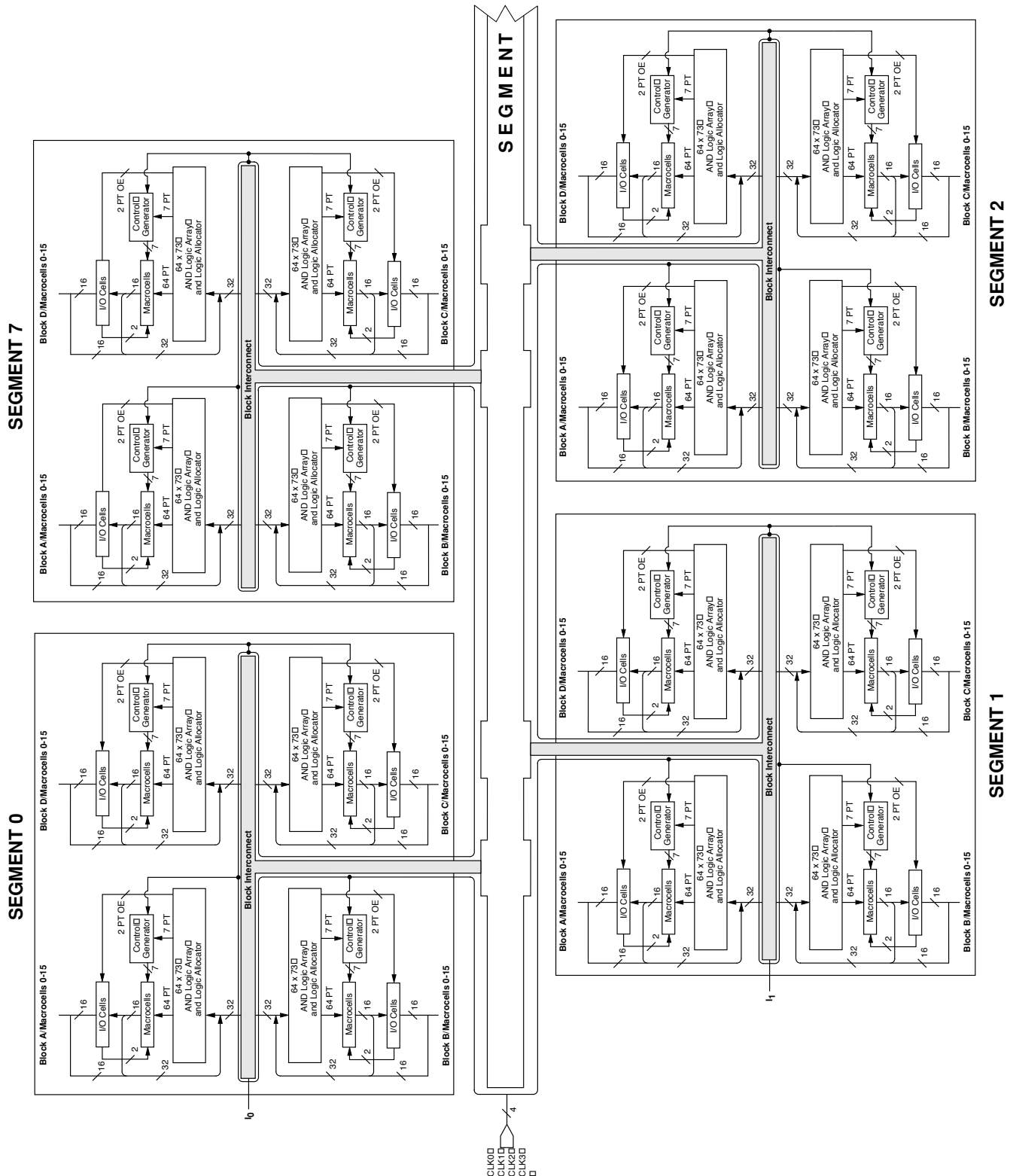


20446G-011

Select devices have been discontinued.
See Ordering Information section for product status.

BLOCK DIAGRAM — M5(LV)-512/XXX

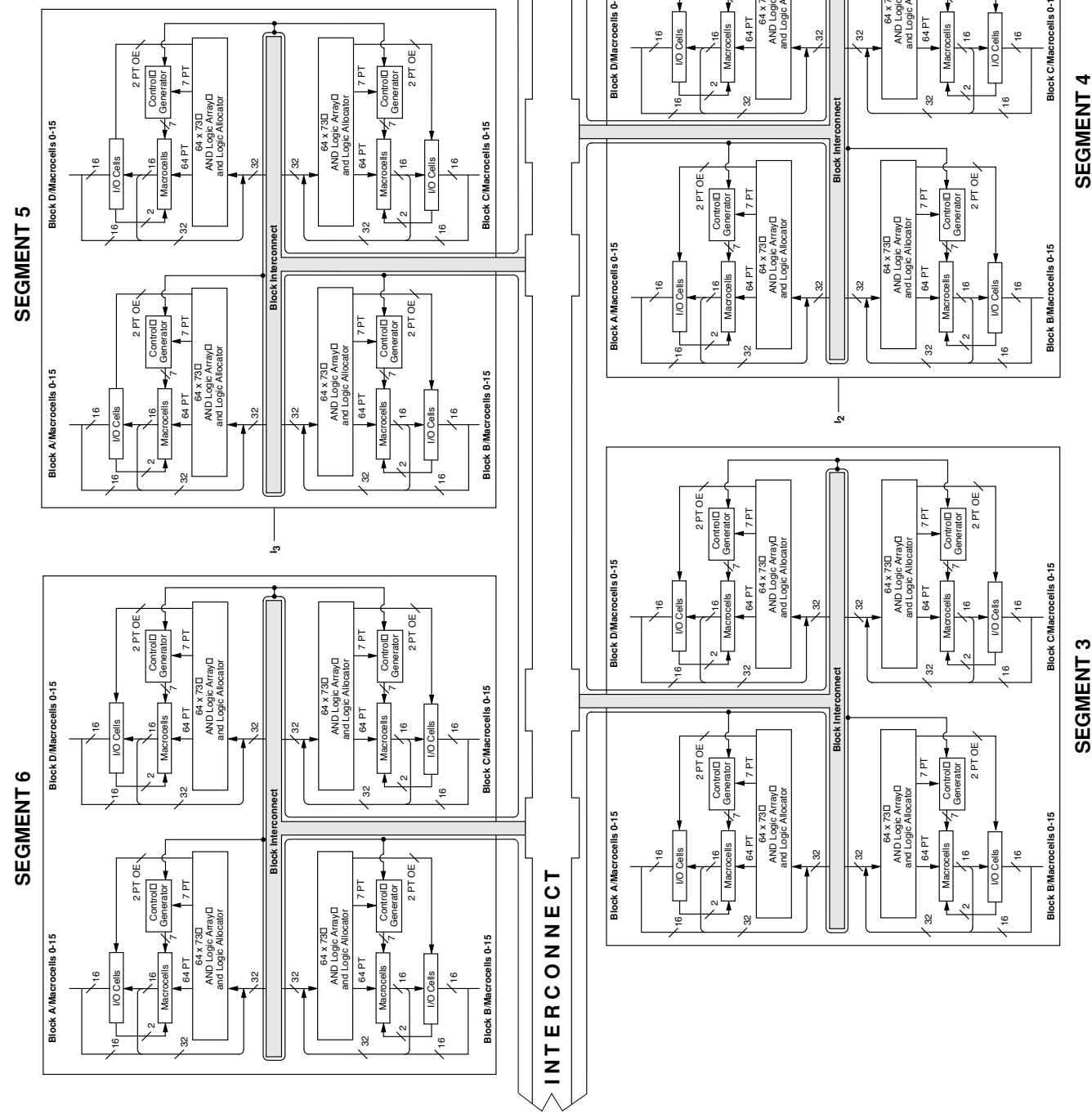
Continued



Select devices have been discontinued.
See Ordering Information section for product status.

20446G-012

BLOCK DIAGRAM — M5(LV)-512/XXX



Continued

Select devices have been discontinued.
See Ordering Information section for product status.

ABSOLUTE MAXIMUM RATINGS

M5LV

Storage Temperature. -65°C to +150°C
 Device Junction Temperature. +130°C
 Supply Voltage
 with Respect to Ground -0.5 V to +4.5 V
 DC Input Voltage -0.5 V to 5.5 V
 Static Discharge Voltage 2000 V
 Latchup Current (-40°C to +85°C) 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)
 Operating in Free Air. 0°C to +70°C
 Supply Voltage (V_{CC})
 with Respect to Ground. +3.0 V to +3.6 V

Industrial (I) Devices

Ambient Temperature (T_A)
 Operating in Free Air. -40°C to +85°C
 Supply Voltage (V_{CC})
 with Respect to Ground. +3.0 V to +3.6 V
Operating ranges define those limits between which the functionality of the device is guaranteed.

Select devices have been discontinued.
See Ordering Information section for product status.

3.3-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Description		Min	Max	Unit
V_{OH}	Output HIGH Voltage	$V_{CC} = \text{Min}$	$I_{OH} = -100 \mu A$	$V_{CC} - 0.2$		V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$	$I_{OH} = 3.2 \text{ mA}$	2.4		V
V_{OL}	Output LOW Voltage	$V_{CC} = \text{Min}$	$I_{OL} = 100 \mu A$		0.2	V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$	$I_{OL} = 16 \text{ mA (Note 1)}$		0.5	V
V_{IH}	Input HIGH Voltage	$V_{OUT} \geq V_{OH} \text{ Min or } V_{OUT} \leq V_{OL} \text{ Max (Note 2)}$		2.0	5.5	V
V_{IL}	Input LOW Voltage	$V_{OUT} \geq V_{OH} \text{ Min or } V_{OUT} \leq V_{OL} \text{ Max (Note 2)}$		-0.3	0.8	V
I_{IH}	Input HIGH Leakage Current	$V_{IN} = 3.6, V_{CC} = \text{Max (Note 3)}$			10	μA
I_{IL}	Input LOW Leakage Current	$V_{IN} = 0, V_{CC} = \text{Max (Note 3)}$			-10	μA
I_{OZH}	Off-State Output Leakage Current HIGH	$V_{OUT} = 3.6, V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 3)}$			10	μA
I_{OZL}	Off-State Output Leakage Current LOW	$V_{OUT} = 0, V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 3)}$			-10	μA
I_{SC}	Output Short-Circuit Current	$V_{OUT} = 0.5 V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 4)}$		-15	-160	mA

Notes:

1. Total I_{OL} between ground pins should not exceed 64 mA.
2. These are absolute values with respect to device ground, and all overshoots due to system and/or tester noise are included.
3. I/O pin leakage is the worst case of I_{IL} and I_{OZL} or I_{IH} and I_{OZH} .
4. Not more than one output should be shorted at one time. Duration of the short-circuit should not exceed one second.

M5(LV) TIMING PARAMETERS OVER OPERATING RANGES¹ (CONTINUED)

		-5		-6		-7		-10		-12		-15		-20		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Power Delays:																
t _{PL1}	Power level 1 delay (Note 2)		4.0 (5.0)		4.0		4.0 (5.0)		4.0 (5.0)		4.0 (5.0)		4.0 (5.0)		4.0 (5.0)	ns
t _{PL2}	Power level 2 delay (Note 2)		6.0 (9.0)		6.0		6.0 (9.0)		6.0 (9.0)		6.0 (9.0)		6.0 (9.0)		6.0 (9.0)	ns
t _{PL3}	Power level 3 delay (Note 2)		9.0 (17.5)		9.0		9.0 (17.5)		9.0 (17.5)		9.0 (17.5)		9.0 (17.5)		9.0 (17.5)	ns
Additional Cluster Delay:																
t _{PT}	Product term cluster delay		0.3		0.3		0.3		0.3		0.3		0.3		0.3	ns
Interconnect Delays:																
t _{BLK}	Block interconnect delay		1.5		1.5		1.5		2.0		2.0		2.0		2.0	ns
t _{SEG}	Segment interconnect delay		4.5		4.5		5.0		6.0		6.0		6.0		6.0	ns
Reset and Preset Delays:																
t _{SRI}	Asynchronous reset or preset to internal register output		6.0		8.0		8.0		10.0		12.0		14.0		16.0	ns
t _{SR}	Asynchronous reset or preset to register output		8.0		10.0		10.0		12.0		14.0		16.0		18.0	ns
t _{SRR}	Reset and set register recovery time	5.5		7.5		7.5		8.0		9.0		10.0		11.0		ns
t _{SRW}	Asynchronous reset or preset width	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
Clock Enable Delays:																
t _{CES}	Clock enable setup time	4.0		5.0		5.0		6.0		7.0		7.0		8.0		ns
t _{CEH}	Clock enable hold time	3.0		4.0		4.0		5.0		6.0		6.0		7.0		ns
Width:																
t _{WLS}	Global clock width low (Note 3)	2.5		3.0		3.0		4.0		5.0		6.0		6.0		ns
t _{WHS}	Global clock width high (Note 3)	2.5		3.0		3.0		4.0		5.0		6.0		6.0		ns
t _{WLA}	Product term clock width low	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
t _{WHA}	Product term clock width high	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
t _{GWA}	Gate width low (for low transparent) or high (for high transparent)	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
t _{WIR}	Input register clock width low or high	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns

Select devices have been discontinued.
See Ordering Information section for product status.

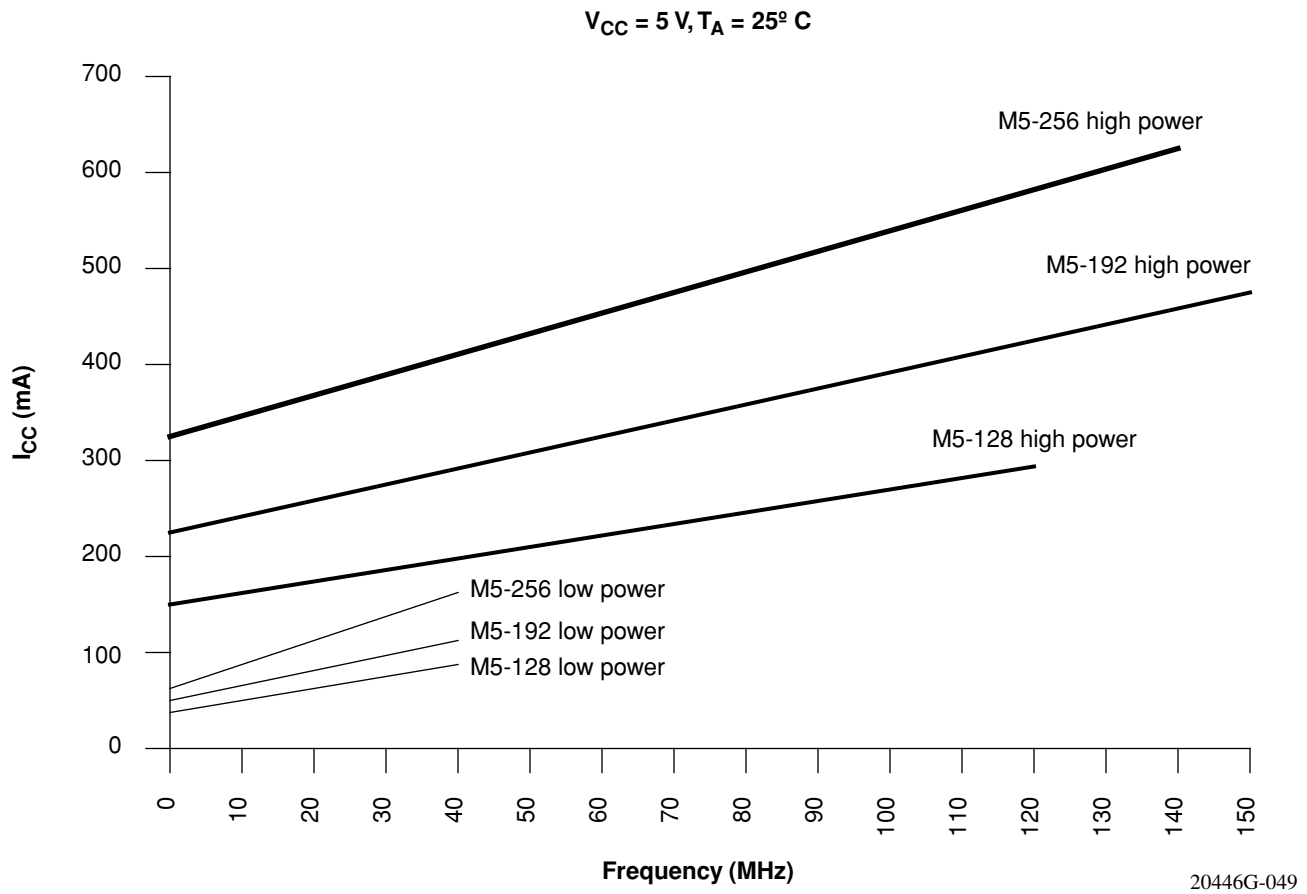


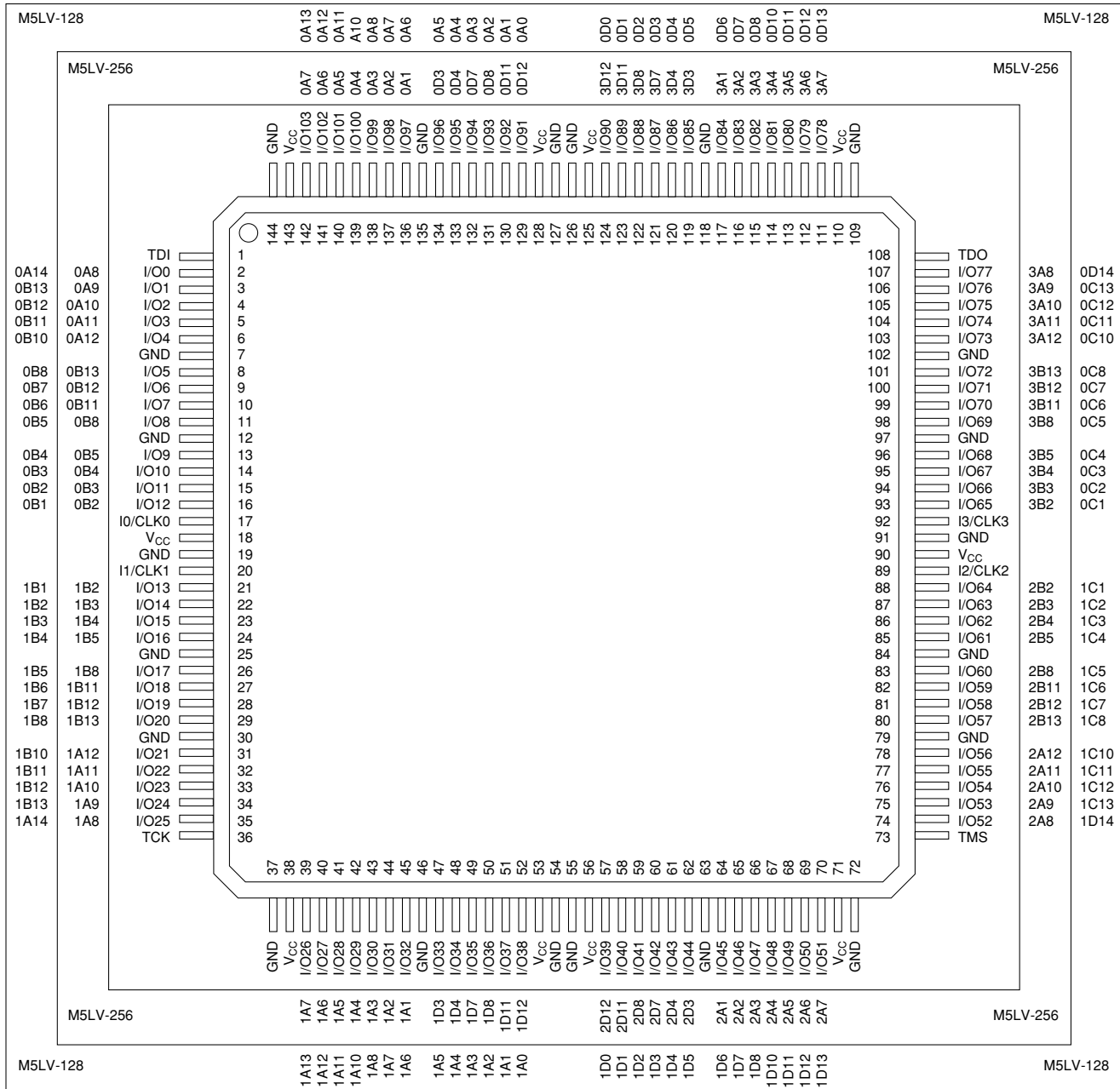
Figure 9. I_{CC} Curves at High/Low Power Modes

Select devices have been discontinued.
See Ordering Information section for product status.

144-PIN TQFP CONNECTION DIAGRAM

Top View

144-Pin TQFP



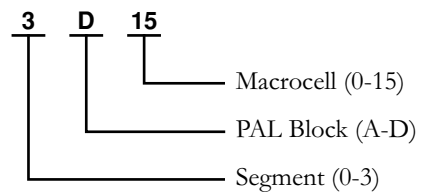
Select devices have been discontinued.
See Ordering Information section for product status.

20446G-020

Pin Designations

CLK = Clock
GND = Ground
I = Input
I/O = Input/Output
NC = No Connect

V_{CC} = Supply Voltage
TDI = Test Data In
TCK = Test Clock
TMS = Test Mode Select
TDO = Test Data Out

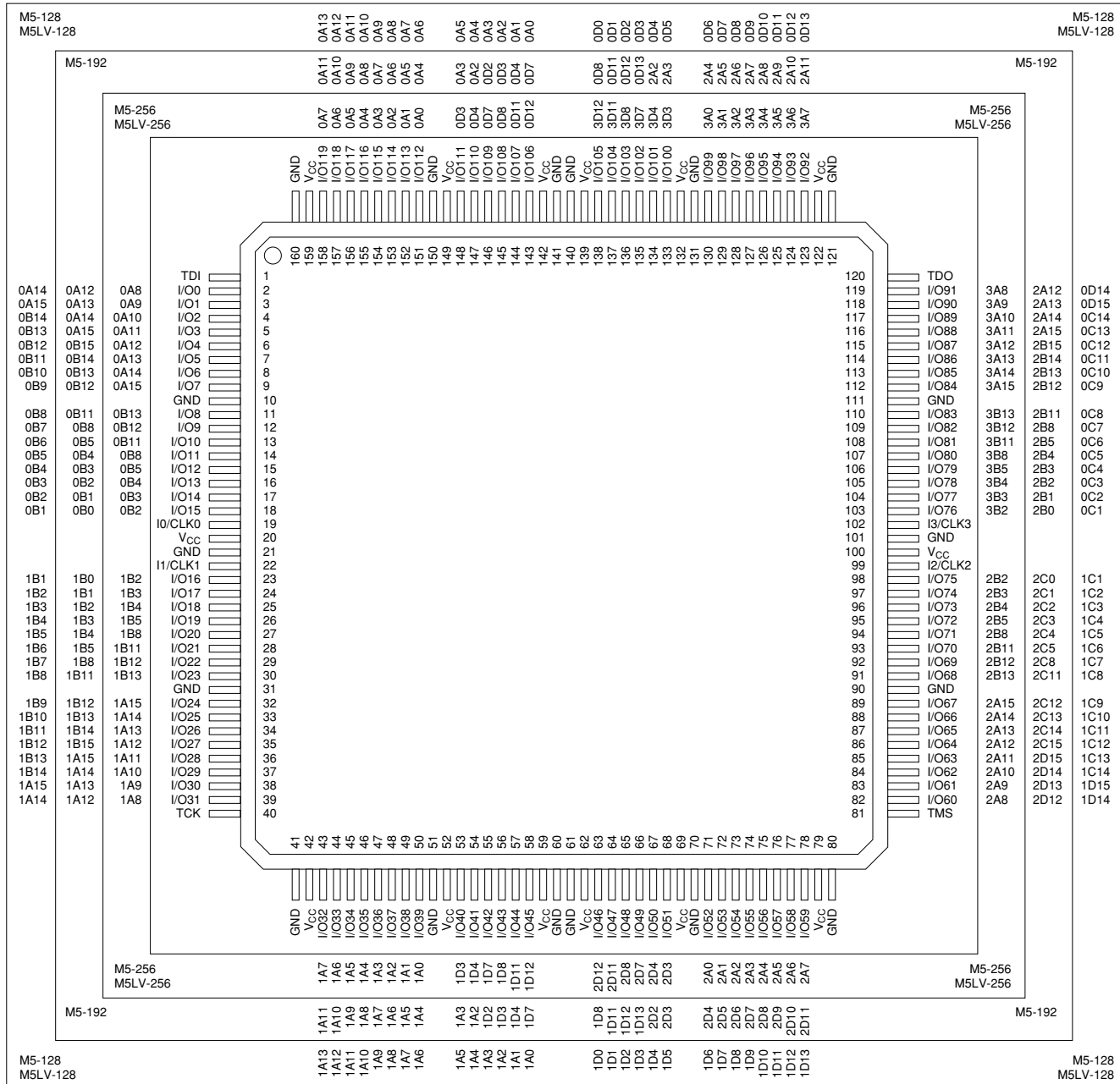


160-PIN PQFP CONNECTION DIAGRAM

Top View

160-Pin PQFP (128, 192, 256 Macrocells)

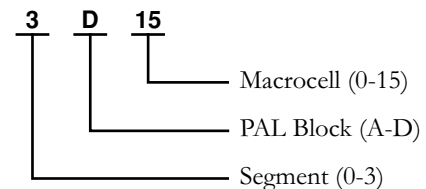
Select devices have been discontinued.
See Ordering Information section for product status.



Pin Designations

CLK = Clock
GND = Ground
I = Input
I/O = Input/Output
NC = No Connect

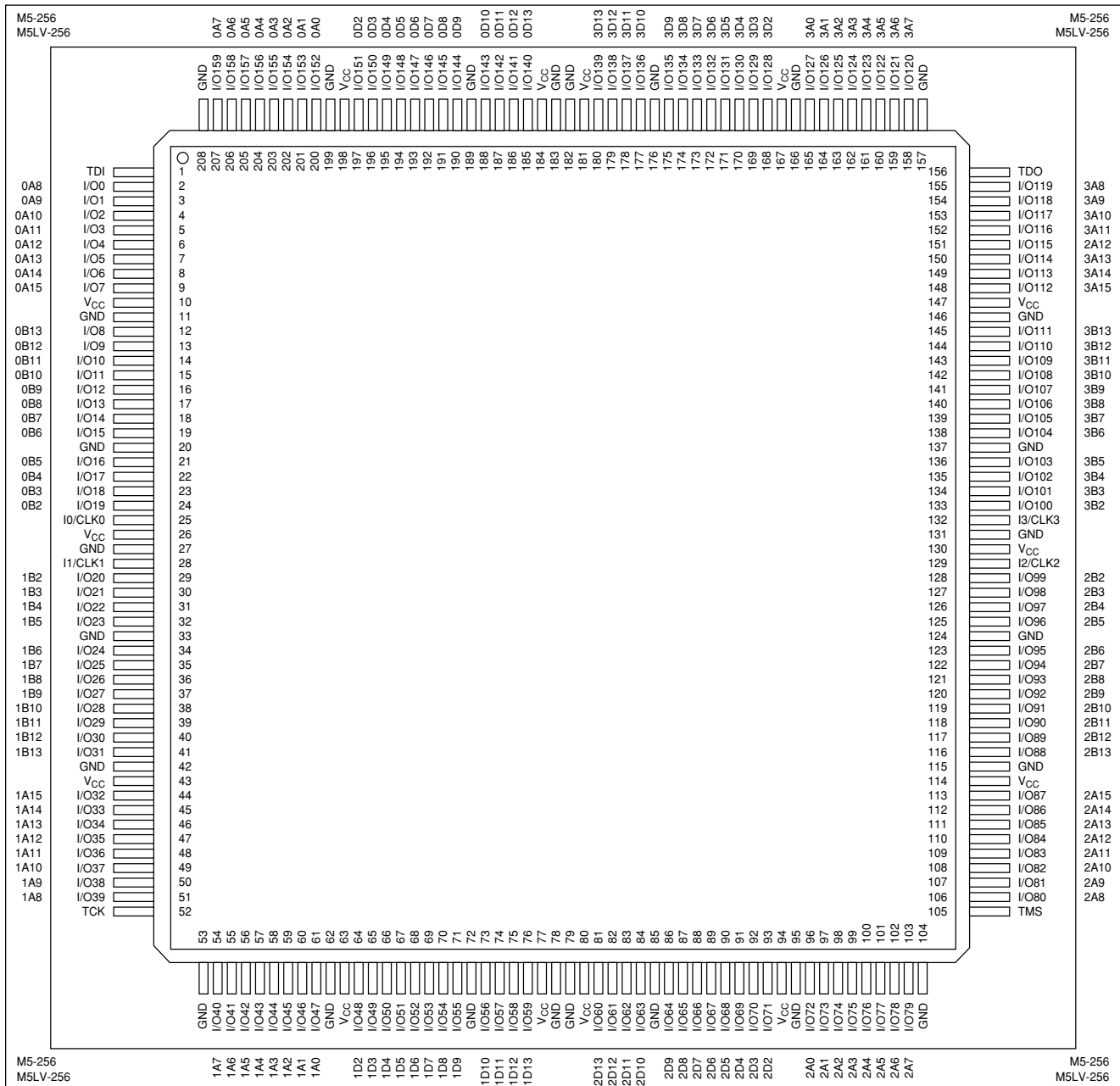
V_{CC} = Supply Voltage
TDI = Test Data In
TCK = Test Clock
TMS = Test Mode Select
TDO = Test Data Out



208-PIN PQFP CONNECTION DIAGRAM

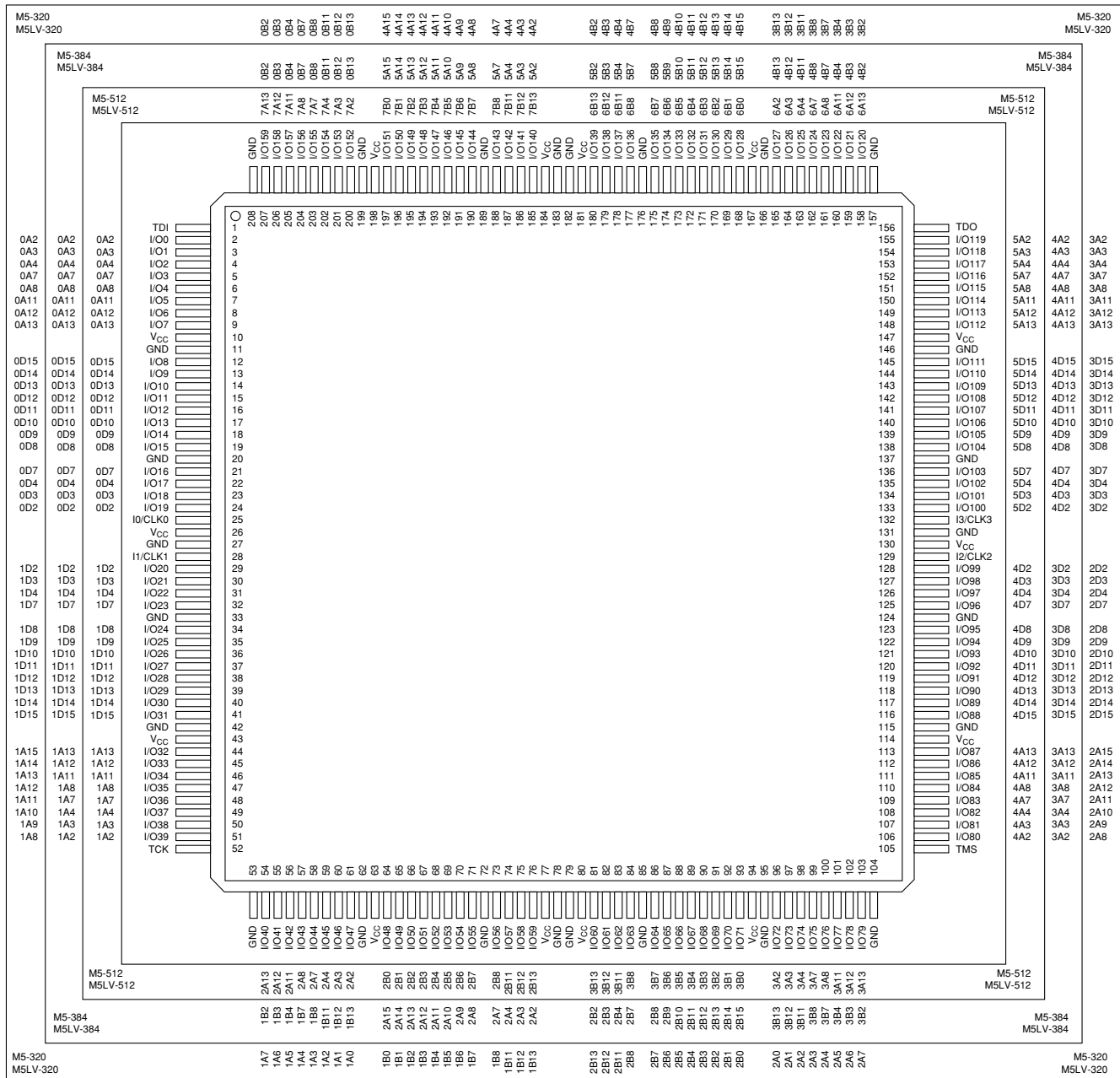
Top View

208-Pin PQFP (256 Macrocells)



208-PIN PQFP (WITH INTERNAL HEAT SPREADER) CONNECTION DIAGRAM Top View

208-Pin PQFP (320, 384, 512 Macrocells)



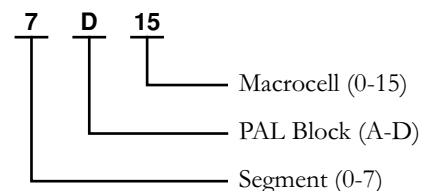
Select devices have been discontinued.
See Ordering Information section for product status.

20446G-024

Pin Designations

CLK = Clock
GND = Ground
I = Input
I/O = Input/Output
NC = No Connect

V_{CC} = Supply Voltage
TDI = Test Data In
TCK = Test Clock
TMS = Test Mode Select
TDO = Test Data Out



256-BALL BGA CONNECTION DIAGRAM — M5-320

Bottom View (I/O Pin-outs)

256-Ball BGA

	A	B	C	D	E	F	G	H	J	K	L	M	N	P	R	T	U	V	W	Y
1	GND	GND	I/O181	I/O182	I/O183	GND	I/O184	GND	I/O185	I/O186	GND	I/O187	GND	I/O188	GND	I/O189	I/O190	I/O191	GND	GND
2	GND	I/O164	I/O165	I/O166	I/O167	I/O168	I/O169	I/O170	I/O171	I/O172	I/O173	I/O174	I/O175	I/O176	I/O177	I/O178	I/O179	I/O180	GND	GND
3	GND	I/O148	V _{CC}	I/O149	I/O150	I/O151	I/O152	I/O153	I/O154	I/O155	I/O156	I/O157	I/O158	I/O159	I/O160	I/O161	I/O162	V _{CC}	I/O163	GND
4	I/O134	I/O135	I/O136	V _{CC}	TDO	I/O137	V _{CC}	I/O138	I/O139	I/O140	I/O141	I/O142	I/O143	V _{CC}	I/O144	TMS	V _{CC}	I/O145	I/O146	I/O147
5	I/O128	I/O129	I/O130	V _{CC}	Pin Designations CLK = Clock GND = Ground I = Input I/O = Input/Output NC = No Connect V _{CC} = Supply Voltage TDI = Test Data In TCK = Test Clock TMS = Test Mode Select TDO = Test Data Out	GND	I/O116	I/O108	GND	GND	GND	GND	I/O76	I/O70	GND	I/O58	I/O44	GND	I/O11	GND
6	I/O122	I/O123	I/O124	V _{CC}		I/O117	I/O109	I/O103	I/O97	I/O96	I/O90	I/O84	I/O77	I/O71	I/O64	I/O59	I/O45	I/O28	I/O12	GND
7	I/O118	I/O110	V _{CC}	I/O111		I/O104	I/O98	I/O92	I/O86	I/O78	I/O72	I/O65	I/O60	V _{CC}	I/O46	V _{CC}	I/O30	I/O15	I/O14	I/O1
8																				
9																				
10																				
11																				
12																				
13																				
14																				
15																				
16	I/O58	I/O59	I/O60	V _{CC}																
17	I/O44	I/O45	I/O46	V _{CC}		TDI	I/O47	V _{CC}	I/O48	I/O49	I/O50	I/O51	I/O52	I/O53	V _{CC}	I/O54	TCK	V _{CC}	I/O55	I/O56
18	GND	I/O28	V _{CC}	I/O29	I/O30	I/O31	I/O32	I/O33	I/O34	I/O35	I/O36	I/O37	I/O38	I/O39	I/O40	I/O41	I/O42	V _{CC}	I/O43	GND
19	I/O11	I/O12	I/O13	I/O14	I/O15	I/O16	I/O17	I/O18	I/O19	I/O20	I/O21	I/O22	I/O23	I/O24	I/O25	I/O26	I/O27	I/O28	I/O29	I/O30
20	GND	GND	I/O0	I/O1	I/O2	GND	I/O3	GND	I/O4	GND	I/O5	I/O6	GND	I/O7	GND	I/O8	I/O9	I/O10	GND	GND

20446G-026

Select devices have been discontinued.
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Bottom View (Macrocell Association)

352-Ball BGA

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